

### **In the Specification**

Please **amend the paragraph** beginning on line 13 of page 3 as follows.

The method is based on the insight that when placing adhesive dots in a regular pattern, the first dots which are delivered by a dot-placing nozzle after an interruption of the placing operation tend to differ in volume from the dots delivered in continuous operation. Such a volume variation may already result from the fact that the delivery of adhesive by the nozzle is interrupted for the time the nozzle takes to move from the contact surface of one circuit component to the contact surface of the next one. By placing fore-running adhesive dots inside the contact surface before beginning to place the dots of the regular pattern, essentially two effects are achieved. On the one hand, the volume of the adhesive dots placed after the fore-running adhesive dots is stabilized, so that the dots of the regular pattern have a uniform volume; on the other hand, the fact that the density of the adhesive in the area of the fore-running dots is increased with respect to the rest of the regular pattern causes the merging of the adhesive dots the to begin at the fore-running dots, when the circuit component and the circuit board are pressed against each other, and a void-free adhesive layer to expand continuously from the region surrounding the fore-running dots to the edges of the contact surface, air being expelled continuously from between the circuit board and the circuit component towards the edges of the contact surface, while the circuit component and the circuit board approach each other.

**Please amend the paragraph** beginning on line 8 of page 6 as follows.

The dispenser head 3 is moved over the contact surface 2 along a meandering track 12 represented as a dashed line at a constant speed, while approaching the surface at regular time intervals in order to place an adhesive dot ~~13~~ <sup>4</sup> thereupon. During this movement of the dispenser head 3, the worm 9 rotates continuously, so that the delivered adhesive quantity is the same for each dot ~~13~~ <sup>4</sup>. In this way, a regular pattern of dots arranged in rows and columns is obtained.

**Please amend the paragraph** beginning on line 19 of page 7 as follows.

From the position shown in Fig. 2, in which the edges of the circuit component 17 are aligned with those of the contact surface 2, the gripper 18 with the circuit component 17 is descended vertically, so that the circuit component comes into contact with the adhesive dots ~~13~~ <sup>4</sup>, 14, 15.